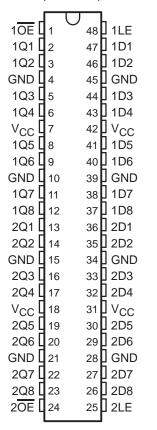
SCBS469 - FEBRUARY 1991 - REVISED OCTOBER 1992

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes
 PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings

description

The 4ABT16373 is a 16-bit transparent D-type latch with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

SN54ABT16373...WD PACKAGE SN74ABT16373...DL PACKAGE (TOP VIEW)



The device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

The output enable (\overline{OE}) does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16373 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16373 is characterized for operation from –40°C to 85°C.

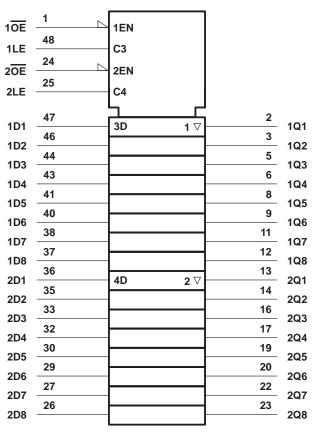
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FUNCTION TABLE (each latch)

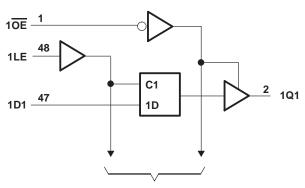
	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	X	Χ	Z

logic symbol†

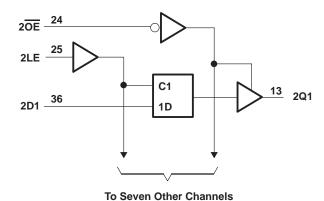


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5	V to 7 V
Input voltage range, V _I (see Note 1)	0.5	V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O	-0.5 V	to 5.5 V
Current into any output in the low state, IO: SN54ABT16373		96 mA
SN74ABT16373		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		-50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air)		0.85 W
Storage temperature range	-65°C to	o 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 2)

			SN54AE	3T16373	SN74AE	3T16373	LINUT
			MIN	MAX	MIN	MAX	UNIT
VCC	V _{CC} Supply voltage				4.5	5.5	V
VIH	High-level input voltage				2		V
V _{IL}	Low-level input voltage		0.8		8.0	V	
٧ _I	Input voltage		0	VCC	0	VCC	V
lOH	High-level output current		Ö	-24		-32	mA
lOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate Outputs enabled		Q' _Q	10		10	ns/V
TA	Operating free-air temperature			125	-40	85	°C

NOTE 2: Unused or floating inputs must be held high or low.



NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS			T _A = 25°C			SN54ABT16373		SN74ABT16373	
PARAMETER				TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V}, \qquad I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V}, I_{OH} = -3 \text{ mA}$					2.5		2.5		
V	$V_{CC} = 5 \text{ V}, \qquad I_{OH} = -3 \text{ mA}$					3		3		V
VOH	$V_{CC} = 4.5 \text{ V}, I_{OH} = -24 \text{ m/s}$	4	2 2 [‡]			2				V
	V _{CC} = 4.5 V, I _{OH} = -32 mA							2		
Va	$V_{CC} = 4.5 \text{ V}, I_{OL} = 48 \text{ mA}$				0.55		0.55			V
VOL	V_{OL} $V_{CC} = 4.5 \text{ V}, I_{OL} = 64 \text{ mA}$				0.55‡				0.55	V
Ц	$V_{CC} = 5.5 \text{ V}, V_I = V_{CC} \text{ or } C$	$V_{CC} = 5.5 \text{ V}, V_{I} = V_{CC} \text{ or GND}$			±1		E		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$			50		50		50	μΑ
lozL	$V_{CC} = 5.5 \text{ V}, V_{O} = 0.5 \text{ V}$				-50	4	-50		-50	μΑ
l _{off}	$V_{CC} = 0$, V_{I} or $V_{O} \le 4.5$	5 V			±100	ζ),	,		±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50	Pa	50		50	μΑ
ΙΟ§	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.5 \text{ V}$		-50	-100	-180	-50	-180	-50	-180	mA
		Outputs high			2		2		2	
ICC	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low			85		85		85	mA
	Outputs disabled				2		2		2	
Δl _{CC} ¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
Ci	V _I = 2.5 V or 0.5 V			3.5						pF
Co	V _O = 2.5 V or 0.5 V			9.5						pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} = 5 V, T _A = 25°C		SN54ABT16373	SN74ABT16373		UNIT
		MIN	MAX	MIN MAX	MIN	MAX	
t _W	Pulse duration, LE high	3.3		3.3	3.3		ns
t _{su}	Setup time, data before LE↓	1.5		1.5	1.5		ns
t _h	Hold time, data after LE↓	1		Q.	1		ns

[‡] On products compliant to MIL-STD-883, Class B, this parameter does not apply.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

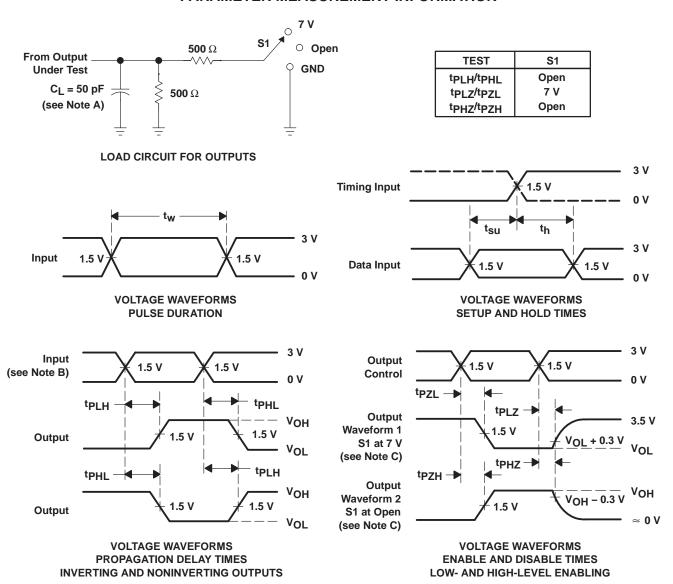
This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO		CC = 5 \ A = 25°C		SN54AB	T16373	SN74AB	T16373	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	D	_	1.9	4.1	5.3	1.9	6.5	1.9	6.3	
^t PHL		Q	2.3	4.3	5.4	2.3	6.5	2.3	6.2	ns
t _{PLH}		_	2.1	4.5	5.7	2.1	7	2.1	6.7	
^t PHL	LE	Q	2.6	4.5	5.6	2.6	6.3	2.6	6.1	ns
^t PZH	ŌĒ		1.5	3.9	5	1.5	6.4	1.5	6.1	
tPZL	OE .	Q	1.8	3.8	4.9	1.8	5.8	1.8	5.6	ns
^t PHZ	ŌĒ	Q	2.4	6.5	8.8	2.4	10.8	2.4	10.3	ns
^t PLZ	OE	Q	2.3	5.3	7.6	2.3	8.7	2.3	8.1	115

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT16373DGGR	OBSOLETE	TSSOP	DGG	48	TBD	Call TI	Call TI
SN74ABT16373DL	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI
SN74ABT16373DLR	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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